



# Sirius Vacuum System

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## Outline



- General requirements
- Storage ring
  - Design concept
    - Chamber materials
    - Pumping
  - Vacuum chamber layout
  - Cleaning process and NEG coating
  - Installation and Bake-out
- Summary





- Fit to compact lattice and small aperture magnets:
  - Tight manufacturing tolerances: average clearance with magnets < 0.5 mm</li>
- Average vacuum < 1 x 10<sup>-9</sup> mbar (CO eq.) in order to guarantee a beam lifetime > 5 hours (at 500 mA)
- Impedance/HOM issues:
  - Keep down the beam impedance and HOM power
  - No steps inside the chambers, i.e. welds, flanges, etc.
  - Transitions must be carefully studied by EM simulation
- No radiation hitting uncooled surfaces
- Quick vacuum recovery, either after start-up or after any venting to the atmosphere pressure
- Finally, the vacuum system must be reliable and cost-effective



### Storage ring: Design concept - chamber materials

Copper	Material	Thermal expansion coefficient [1/C°]	Electrical conductivity [%IACS]	Thermal conductivity [W/m.K]	Young Modulus load [GPa]	Yield Strength [MPa]
	Copper OF w/ silver (UNS C107)	17.7	100	388	115	250

### Effect of Silver on copper

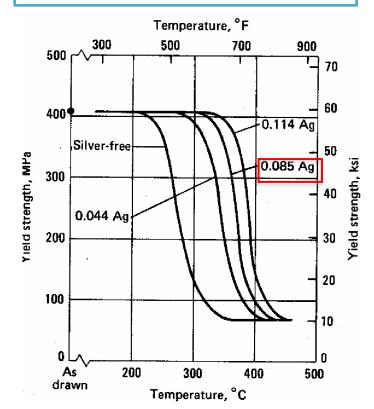
### **Stainless steel:**

- Flanges
- Pumping ports

### Alumina:

• Small sectors for fast orbit correctors

OBS: electron beam will not face the stainless steel or alumina parts





## Storage ring: Design concept - pumping



### **Pumping philosophy:**

- Extensively use of **NEG coating** chambers will be full NEG coated:
  - Chambers in electron beam path (except RF-cavities, bellows, valves and BPMs);
  - Pumping ports.
- Small **ion pumps** will be used to pump gases not pumped by the NEG coating (hydrocarbons and noble gases);

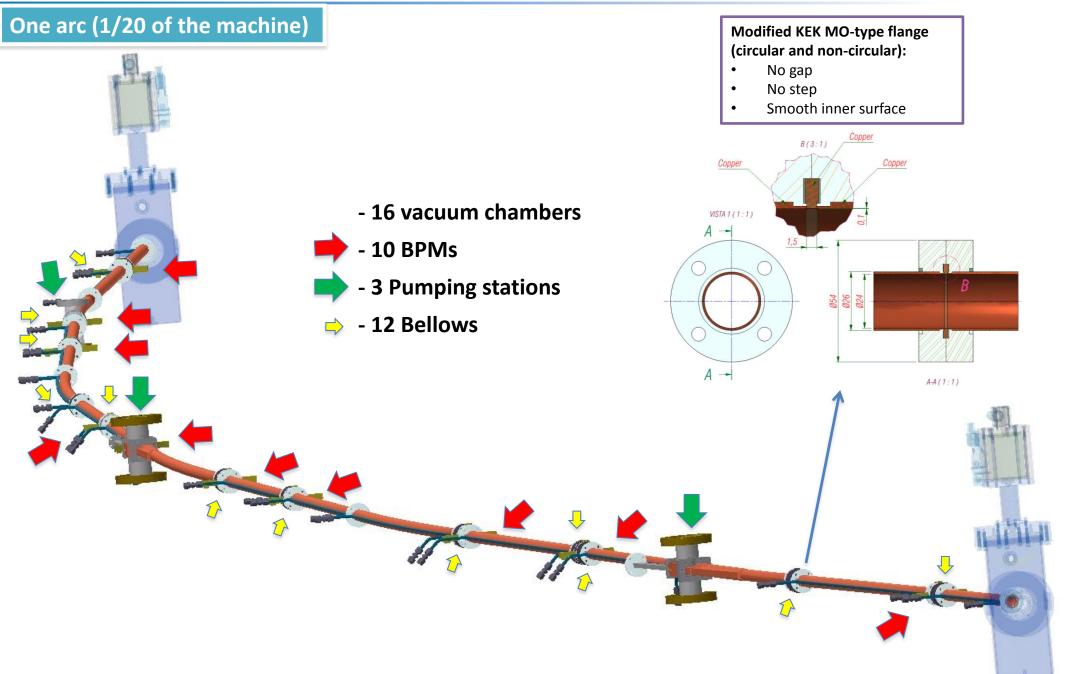
A license agreement between CERN and LNLS has been signed – NEG thin film technology transfer

OBS.: NEG coating is a well established technology, used in many places: LHC (more than 6 km of chambers); Soleil (56% of the chambers); proposed for MAX-IV (all chambers of the storage ring); and many other places (ID's and other chambers).



## Storage ring: Vacuum chamber layout







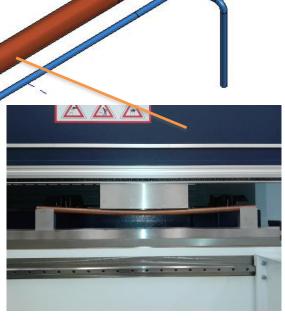
Vacuum brazing

## Storage ring: Vacuum chamber layout



#### Main manufacturing processes to be used: Machining Wire cutting (EDM) • High temperature brazing • Copper TIG welding • Low temperature brazing ightarrowPrecise bending • Copper cleaning/etching $\bullet$ NEG coating TIG welding

TIG welding



Vacuum brazing

TIG welding

Needs careful handle between processes to maintain the tight tolerances!

Vacuum brazing



### Storage ring: Cleaning process and NEG coating



### Manufacturing developments: final **cleaning**

- Based on recirculation system with a peristaltic pump:
  - 6 chambers cleaned each time;
  - Less acid volumes needed
  - Better cleaning efficiency
  - Only copper is exposed to the cleaning solutions
- Cleaning Procedure under study:
  - Degreasing with alkaline detergent
  - ✓ 10% ammonium persulfate etch about 50 µm (remove extrusion defects)
  - 0.5% sulfamic acid + 4%
    hydrogen peroxide (remove persulfate residues)
  - ✓ 5% ammonium citrate (passivation)
  - ✓ Water rinsing

### Built cleaning facility



### Cleaning OFS copper is very tricky!



## Storage ring:



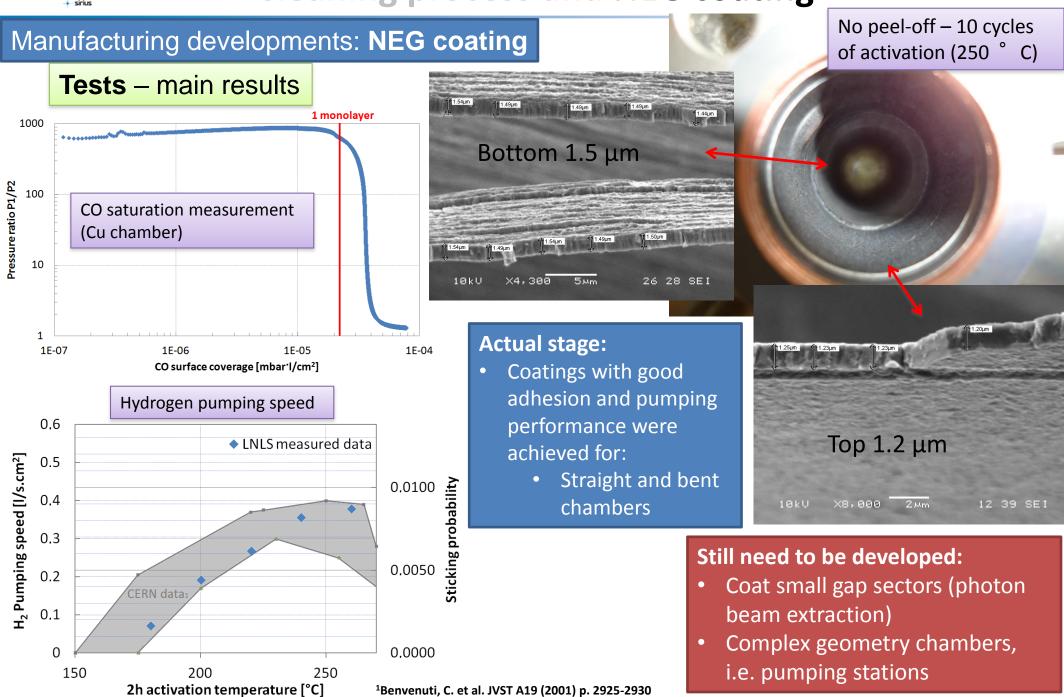
## **Cleaning process and NEG coating**



• Automatic control of the whole deposition run

# Storage ring:Laboratório Nacional<br/>de Luz SincrotronCleaning process and NEG coating





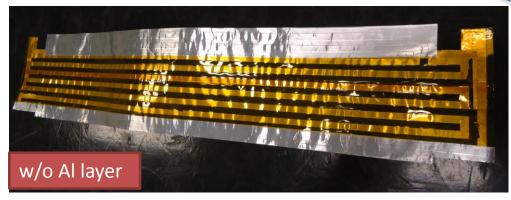


## Storage ring: Installation and Bake-out

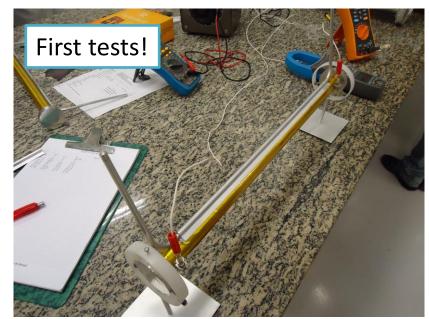


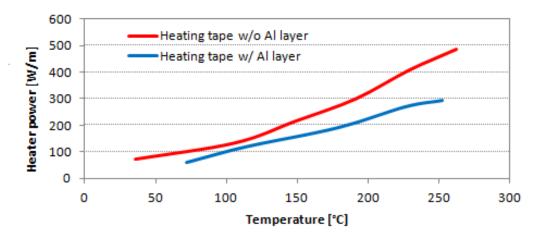
- 1. After NEG coating, the chambers will be filled with  $N_2$  and stored
- 2. In-situ assembling the chambers with half of the magnets in place
- 3. Make all electrical and hydraulic connections
- 4. Close magnets

- 5. In-situ bake-out for NEG activation (200 °C @ 24h):
  - An thin polyimide heating tape will be used:
    - Thickness < 0.4 mm
    - Max. tested temperature 250 °C













- The chamber's material must be carefully chosen, because its cleaning process, **prior to NEG coating,** can be very tricky;
- The design of the chambers must take into account the different manufacturing processes and their sequence:
  - Cleaning process and NEG coating **must be feasible** for the designed components, i.e. small gaps, complex geometries, different materials, etc.
  - **Pay attention** to EDM process, because it can leave surface contaminats (not compatible with UHV and NEG coating) that comes from the wire;
- The number of needed bellows and the design of some components **are impacted** by the decision of **in-situ** or **ex-situ NEG activation**.
- All NEG films should be visually inspected, it is not so accurate and should be done by trained people. Endoscopes can be used to help in the visual inspection, but care must be taken not to contaminate or damage the film.